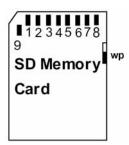
Description

TS2GSDC is a 2GB Secure Digital Card of high capacity but economic cost. It is specifically designed to meet the security, capacity and small form factor requirements in newly emerging audio and video consumer electronic devices.TS2GSDC can lead you to a colorful digital world.

Placement





Back

Features

• Storage Capacity: 2GB(2GBitX8)

• Operating Voltage: 2.7 ~ 3.6V

• Operating Temperature: -25 ~ 85°C

• Durability: 10,000 insertion/removal cycles

• Fully compatible with SD card spec. v1.1

• Mechanical Write Protection Switch

SD Host allows MultiMediaCard upward compatibility

 Supports Copy Protection for Recorded Media(CPRM) for SD-Audio

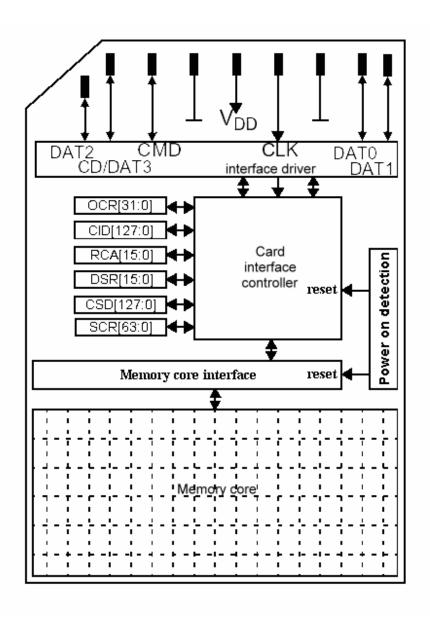
Seamless compatibility with SDMI-compliant digital audio
devices.

• Form Factor: 24mm x 32mm x 2.1mm

Pin Definition

Pin No.	SD Mode					SPI Mode
FIII NO.	Name Type Description		Name	Type	Description	
1	CD/DAT	I/O/PP ³	Card Detect/Data Line [Bit3]	CS	I	Chip Select (neg true)
2	CMD	PP	Command/Response	DI	Ι	Data In
3	V_{SS1}	S	Supply voltage ground	VSS	S	Supply voltage ground
4	V_{DD}	S	Supply voltage	VDD	S	Supply voltage
5	CLK	I	Clock	SCLK	Ι	Clock
6	V_{SS2}	S	Supply voltage ground	VSS2	S	Supply voltage ground
7	DAT0	I/O/PP	Data Line [Bit0]	DO	O/PP	Data Out
8	DAT1	I/O/PP	Data Line [Bit1]	RSV		
9	DAT2	I/O/PP	Data Line [Bit2]	RSV		

Architecture



Bus Operating Conditions

General

Parameter	Symbol	Min.	Max.	Unit	Remark	
Peak voltage on all lines		-0.3	VDD+0.3	V		
All Inputs						
Input Leakage Current		-10	10	μΑ		
All Outputs						
Output Leakage Current		-10	10	μΑ		

Power Supply Voltage

Parameter	Symbol	Min.	Max.	Unit	Remark
Supply voltage	V_{DD}	2.0	3.6	V	CMD0, 15,55,ACMD41
					commands
Supply voltage specified in OCR register		2.7	3.6	V	Except CMD0, 15,55,
					ACMD41 commands
Supply voltage differentials (V _{SS1} , V _{SS2})		-0.3	0.3	V	
Power up time			250	ms	From 0v to V _{DD} Min.

Note. The current consumption of any card during the power-up procedure must not exceed 10 mA.

Bus Signal Line Load

The total capacitance C_L the CLK line of the SD Memory Card bus is the sum of the bus master capacitance C_{HOST} , the bus capacitance C_{BUS} itself and the capacitance C_{CARD} of each card connected to this line:

$$C_L = C_{HOST} + C_{BUS} + N^*C_{CARD}$$

Where N is the number of connected cards. Requiring the sum of the host and bus capacitances not to exceed 30 pF for up to 10 cards, and 40 pF for up to 30 cards, the following values must not be exceeded:

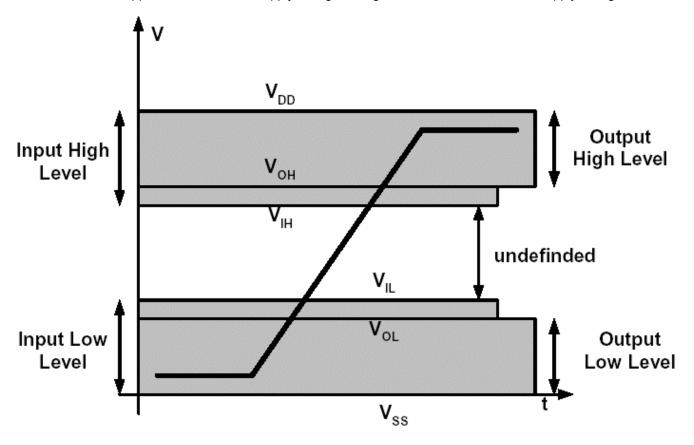
Parameter	Symbol	Min.	Max.	Unit	Remark
Bus signal line capacitance	C_L		100	pF	$f_{PP} \le 20$ MHz, 7 cards
Single card capacitance	C _{CARD}		10	pF	
Maximum signal line inductance			16	nΗ	$f_{PP} \le 20 \text{ MHz}$
Pull-up resistance inside card (pin1)	R _{DAT3}	10	90	kΩ	May be used for card
					detection

Note that the total capacitance of CMD and DAT lines will be consist of C_{HOST} , C_{BUS} and one C_{CARD} only since they are connected separately to the SD Memory Card host.

Parameter	Symbol	Min.	Max.	Unit	Remark
Pull-up resistance	R_{CMD}, R_{DAT}	10	100	kΩ	To prevent bus floating
Bus signal line capacitance	C_L		250	pF	f _{PP} ≤ 5 MHz, 21 cards

Bus Signal Levels

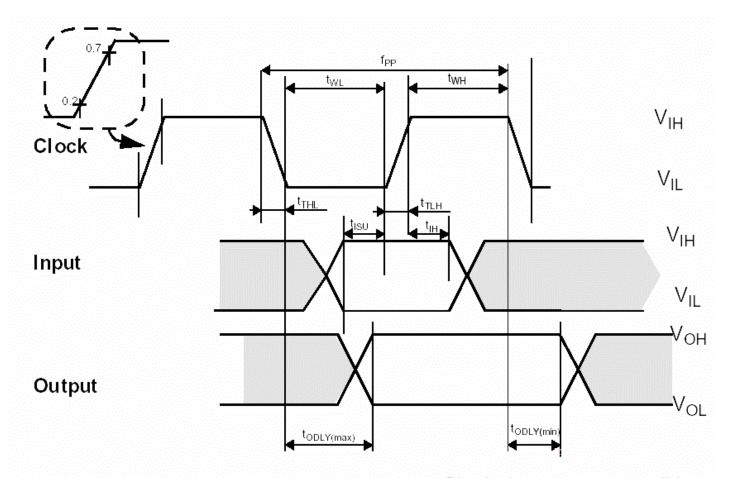
As the bus can be supplied with a variable supply voltage, all signal levels are related to the supply voltage.



To meet the requirements of the JEDEC specification JESD8-1A, the card input and output voltages shall be within the following specified ranges for any V_{DD} of the allowed voltage range:

Parameter	Symbol	Min.	Max.	Unit	Remark
Output HIGH voltage	V _{OH}	0.75* V _{DD}		V	I_{OH} = -100 μ A $@V_{DD}$ min
Output LOW voltage	V _{OL}		0.125* V _{DD}	V	I _{OL} = -100 μA @V _{DD} min
Input HIGH voltage	V _{IH}	0.625* V _{DD}	V _{DD} + 0.3	V	
Input LOW voltage	V _{IL}	$V_{SS} - 0.3$	0.25* V _{DD}	V	

• Bus Timing



Shaded areas are not valid

Parameter	Symbol	Min	Max.	Unit	Remark			
Clock CLK (All values are referred to min (V _{IH})	Clock CLK (All values are referred to min (V _{IH}) and max (V _{IL})							
Clock frequency Data Transfer Mode	f_{PP}	0	25	MHz	C _L ≤ 100 pF, (7 cards)			
Clock frequency Identification Mode	f_{OD}	0	400	KHz	C _L ≤ 250 pF, (21 cards)			
(The low freq. is required for MultiMediaCard compatibility.)								
Clock low time	t _{WL}	10		ns	C _L ≤ 100 pF, (7 cards)			
		50		ns	C _L ≤ 250 pF, (21 cards)			
Clock high time	t_WH	10		ns	C _L ≤ 100 pF, (7 cards)			
		50		ns	C _L ≤ 250 pF, (21 cards)			
Clock rise time	t _{TLH}		10	ns	C _L ≤ 100 pF, (7 cards)			
			50	ns	C _L ≤ 250 pF, (21 cards)			

TS2GSDC

2GB Secure Digital Card

	1	1	1	1			
Clock fall time	t _{THL}		10	ns	$C_L \le 100 \text{ pF, } (7 \text{ cards})$		
			50	ns	C _L ≤ 250 pF, (21 cards)		
Inputs CMD, DAT (referenced to CLK)							
Input set-up time	t _{ISU}	5		ns	$C_L \le 25 \text{ pF, (1 cards)}$		
Input hold time	t _{IH}	5		ns	$C_L \le 25 \text{ pF, (1 cards)}$		
Outputs CMD, DAT (referenced to CLK)							
Output Delay time	t _{ODLY}	0	14	ns	$C_L \le 25 \text{ pF, (1 cards)}$		

Reliability and Durability

Temperature	Operation: -25°C / 85°C (Target spec)
	Storage: -40°C (168h) / 85°C (500h)
	Junction temperature: max. 95°C
Moisture and corrosion	Operation: 25°C / 95% rel. humidity
	Storage: 40°C / 93% rel. hum./500h
	Salt Water Spray: 3% NaCl/35C; 24h acc. MIL STD Method 1009
Durability	10.000 mating cycles; test procedure: tbd.
Bending	10N
Torque	0.15N.m or +/-2.5 deg
Drop test	1.5m free fall
UV light exposure	UV: 254nm, 15Ws/cm² according to ISO 7816-1
Visual inspection	No warp page; no mold skin; complete form; no cavities surface smoothness <=
Shape and form	-0.1 mm/cm² within contour; no cracks; no pollution (fat, oil dust, etc.)
Minimum moving force of WP witch	40gf (Ensures that the WP switch will not slide while it is inserted to the connector.)
WP Switch cycles	minimum 1000 Cycles(@Slide force 0.4N to 5N)

Above technical information is based on industry standard data and tested to be reliable. However, Transcend makes no warranty, either expressed or implied, as to its accuracy and assumes no liability in connection with the use of this product. Transcend reserves the right to make changes in specifications at any time without prior notice.